

Electronic Patent Application Fee Transmittal

Application Number:	10500381			
Filing Date:	29-Jun-2004			
Title of Invention:	Soi wafer manufacturing method and soi wafer			
First Named Inventor:	Masatake Nakano			
Filer:	Christopher W. Brown/Jori Krischke			
Attorney Docket Number:	120164			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	450	450

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				1240